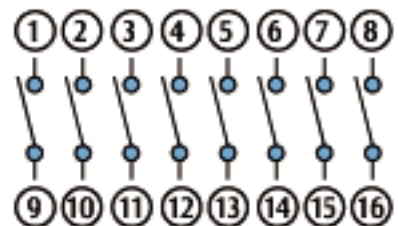
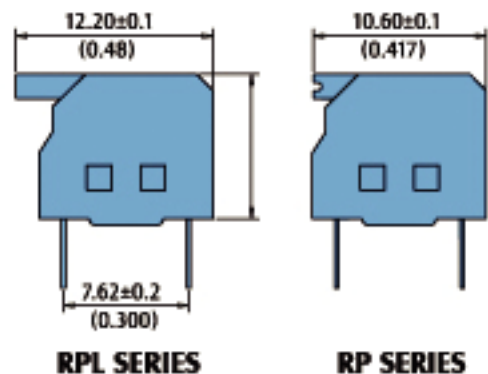
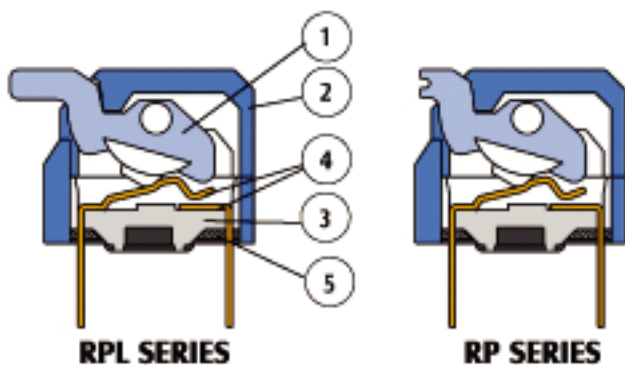

P.C.B. LAYOUT

CIRCUIT DIAGRAM
TERMINAL TYPE

RPL & RP CONSTRUCTION


1. Terminal plating by gold gives excellent results when soldering.
2. RPL series (raised actuator) and RP series (recessed actuator)
3. Low contact resistance, and self-clean on contact area.
4. Double contacts offer high reliability.
5. All materials are UL94V-0 grade fire retardant plastics.

ITEM	Description	Materials	Treatment
1	Actuator	UL94V-0 PBT	White
2	Cover	UL94V-0 PBT	Blue, Red, Black
3	Base	UL94V-0 PBT	Black
4	Terminal Contact	Phosphor bronze	Gold Plating
5	Potting	Epoxy	Black

MODEL

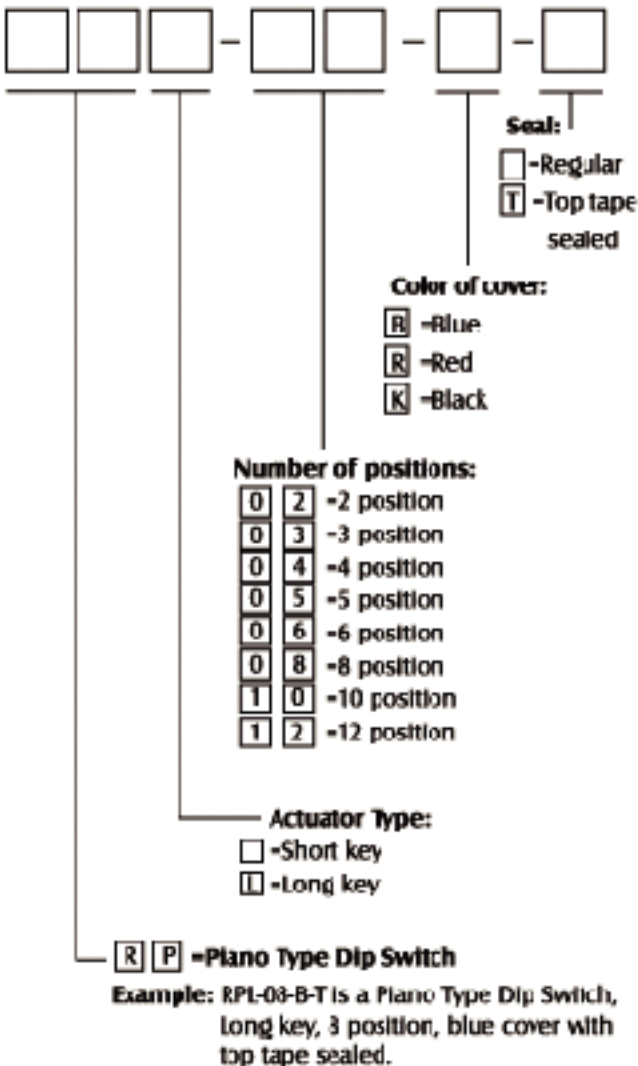
PART NO.	NO. OF POS	DIM A	
RPL/RP-02	02	6.26	0.246
RPL/RP-03	03	9.06	0.357
RPL/RP-04	04	11.34	0.446
RPL/RP-05	05	13.88	0.546
RPL/RP-06	06	16.42	0.646
RPL/RP-08	08	21.5	0.846
RPL/RP-10	10	26.58	1.046
RPL/RP-12	12	31.60	1.244

SPECIFICATION
ELECTRICAL

Electrical life: 2000 operation cycles per switch 24VDC, 25mA.
 Non-Switching Rating: 100mA, 50 VDC
 Switching Rating: 25mA, 24VDC.
 Contact resistance: (a) 50mΩ max. at Initial
 (b) 100mΩ max. after life test.
 Insulation resistance: 100MΩ min. (at 500VDC)
 Dielectric Strength: 500VAC/1 minute.
 Capacitance: 5pF max.
 Circuit: Single pole single throw

MECHANICAL

Mechanical life: 2000 operations per cycle switch
 Operation Force: 400gf max.
 Stroke: 2.0mm
 Operation Temp: -25° C to +70° C
 Storage Temp: -40° C to +85° C
 Vibration Test: MIL-STD-202F METHOD 201A
 Frequency: 10-55-10Hz/1 min
 Directions: X, Y, Z, three mutually perpendicular directions.
 Time: 2 hours each direction.
 High reliability.
 Shock Test: MIL-STD-202F METHOD 213D.
 CONDITION A
 GRAVITY: 50G (peak value), 11 m/sec.
 Direction and times: 6 sides and three times in each direction. High reliability.

HOW TO ORDER

SOLDERING AND CLEANING PROCESSES

For best results, please follow these recommendations:
 Keep all switch contacts in their "OFF" position for all operations.
WAVE SOLDERING: Recommended solder temperature at 500 F (260° C) max. 5 seconds.
HAND SOLDERING: Use a soldering iron of 30 watts, controlled at 608 F (320° C) approximately 2 seconds while applying solder.
CLEANING PROCESS: Flux clean using force rinse, high agitation or triple bath cleaning method. Freon TF or TE give excellent results. When vapor methods are used, do not subject the switch to solvents at temperatures above 125 F (51° C).

PACKING

All Dip Switches are shipped in standard IC tubes with all poles in "OFF" position.